



Material Content Data Sheet



Sales Product Name		BTM7741G		Issued		20. July 2018		
MA#		MA001363468						
Package		PG-DSO-28-22		Weight*		809.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.005	0.87	0.87	8654	8654
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		89	
	non noble metal	zinc	7440-66-6	0.288	0.04		355	
	non noble metal	iron	7439-89-6	5.754	0.71		7108	
wire	non noble metal	copper	7440-50-8	233.637	28.86	29.62	288632	296184
	non noble metal	aluminium	7429-90-5	1.732	0.21	0.21	2140	2140
	encapsulation	organic material	carbon black	1333-86-4	1.106	0.14		1366
encapsulation	plastics	epoxy resin	-	79.082	9.77		97696	
	inorganic material	silicondioxide	60676-86-0	472.832	58.42	68.33	584130	683192
leadfinish	non noble metal	tin	7440-31-5	4.975	0.61	0.61	6146	6146
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	837	837
glue	plastics	epoxy resin	-	0.403	0.05		498	
	noble metal	silver	7440-22-4	1.901	0.23	0.28	2349	2847
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com